

	s Change Notification				
1. PCN No.:	QPCN12008				
2. Subject:	SKY 100V wafer construction change				
3. To:	All customers involved				
4. Issued by:	Owen Wang				
5. Issue date:	9-Apr-2012				
6. Proposed first ship date for change:	14-Jul-2012				
7. Affected Product Identification					
Please see Appendix A – by package type					
8. Change Description : (OLD Vs. NEW Cor					
Old:	New:				
See appendix B	See appendix B				
9. Reason for Change:					
Unify all SKY (60V, 100V, 160V,) layout, fro	ntend processes.				
10. Anticipated Impact: (form, fit, function, qu	uality or reliability)				
Product outline: No chan	ge				
<u> </u>	Please see Appendix B – by Passivation/Metallization				
•	No change				
<i>y</i> 1	ease of reliability based on influence of CIP (Continuous				
	Improvement Process) No change				
	o change				
11.Qualification plan/result:					
Refer to					
PPAP Available on	demand				
Comparison report Available on demand					
12. Sample availability Date:	Apr-2012				
13. Tentative implementation date:	9-May-2012				
14. Remarks					
15. Customer feedback required latest:	9-May-2012				
(should we receive no feedback; the change					
will be deemed as accepted!)	Quayer Chen				
16. Approved by:	I ()UOVOR ('hon				



Product/ Process Change Notification Customer Approval Form_QPCN12008

(Please tick the field what is valid for you!)				
We agree with this proposed change and its schedule.				
We have object	tions			
We need more	information:			
We need samp	le:			
Company:				
Name:				
Address:				
Signature		Date:		
Signature:		Date.		



Product/ Process Change Notification Appendix

A (Affected product Identification): by package type

Sub SMA	SMA	SMB		SMC
SS110L	SS110	SK110B	SK310B	SS310
SS210L	SK210A	SS210	SK510B	SK510C
	SK310A	SSH210		
I2PAK	TS-1	DO-41	DO-15	DO-201AD
MBRI20100CT	SRT110	SR010	SR210	SR310
MBRI30100CT		SR110		SR510
				SR810
ITO-220AB		TO-220AB		TO-220AC
MBRF8100CT	MBRF20100CT	MBR10100CT	MBR20L100CT	MBR7100
MBRF10100CT	MBRF20100D	MBR10H100CT	SR20100	SRA8100
MBRF10H100CT	MBRF20H100CT	MBR10L100CT	MBR25100CT	MBR10100
MBRF10L100CT	MBRF20L100CT	SR10100	MBR30100CT	SRA10100
MBRF10100D	SRF20100	MBR15100CT	MBR30H100CT	MBR16100
SRF10100	MBRF25100CT	SR16100	MBR30L100CT	SRA16100
MBRF15100CT	MBRF30100CT	MBR20100CT		SRA20100
SRF16100		MBR20H100CT		
ITO-220AC	TO-3P		D2PAK	
MBRF5100	SR16100PT	MBR40100PT	SRAS8100	SRS16100
SRAF5100	MBR20100PT	SR40100PT	MBRS10100	MBRS20100CT
MBRF7100	SR20100PT	MBR60100PT	MBRS10100CT	MBRS20H100CT
SRAF8100	MBR30100PT		MBRS10H100CT	SRAS20100
MBRF10100	SR30100PT		SRS10100	SRS20100
SRAF10100			MBRS15100CT	MBRS25100CT
MBRF16100			MBRS16100	
SRAF16100				
MBRF20100				



Product/ Process Change Notification Appendix

B (Anticipated Impact to inner construction changed): by Passivation/Metallization

	Before	After
N+	Yes	No
Oxide	10um	20um
Drawing of profile	P. P.	P. P.
Drawing of zoom profile	Oxide Al SiO2 Ti	Oxide SiO2 Ti
Photo	W22.3mm 2/90 Seim	20KU X1,100 10Mm 19 29 SEI
Etching process	Etching front metal process	Add backing Al/Ni/Au etching process